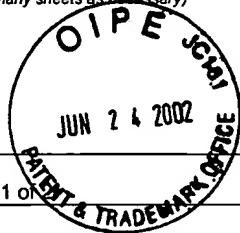


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<b>Application Number</b>	09/944983
<b>Filing Date</b>	August 30, 2001
<b>First Named Inventor</b>	Farrar, Paul
<b>Group Art Unit</b>	Unknown
<b>Examiner Name</b>	Unknown

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Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T <sup>2</sup>

**OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS**

Examiner Initials*	Cite No <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>2</sup>
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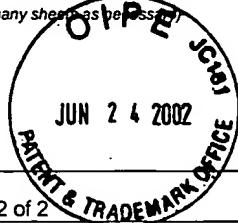
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<b>Group Art Unit</b>	Unknown
<b>Examiner Name</b>	Unknown

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